

--36 The optical transmission device as defined in claim 30, further comprising: a plug connected to the optical element.--

REMARKS

Claims 1-26, 28-33 and 35-36 are pending. By this Preliminary Amendment, the specification and claims are amended. Claims 27 and 34 are cancelled without prejudice to or disclaimer of the subject matter contained therein. Claims 35 and 36 are added. Prompt and favorable examination on the merits is respectfully requested.

The attached Appendix includes marked-up copies of each rewritten paragraph (37 C.F.R. §1.121(b)(1)(iii)) and claim (37 C.F.R. §1.121(c)(1)(ii)).

Respectfully submitted,



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APPENDIX

Changes to Specification:

The following is a marked-up version of the amended paragraph:

Page 14, lines 14-22 are deleted.

Page 16, lines 18-24 are deleted.

Page 14, between lines 13 and 23, a new paragraph is added.

Page 16, between lines 17 and 24, a new paragraph is added

The following is a marked-up version of the amended paragraph:

Page 18, lines 14-24:

When the mold 10 is formed of a material such as silicon or the like to which the metal of which the wire is formed does not adhere easily, a bonding pad 24 is preferably previously formed on the mold 10. The bonding pad 24 may be a conductive film or if not electrically conductive, a film such that the wire can be attached. In this case, the wire and ~~conductive layer 24~~ bonding pad 24 integrally form the interconnecting line 20. The surface of the bonding pad 24 may be formed of the same material as the wire. For example, when the wire is of gold, the bonding pad 24 may be formed of a film of chromium, with a film of gold formed thereon.

Page 19, line 20 to page 20, line 2:

Then, the ends of pins 32 and 34 are disposed facing the mold 10. In more detail, the pins 32 and 34 are inserted into the hole 16 formed in the mold 10. The pin 32 is fixed to the upper die 36, and when the upper die 36 and lower die 38 are closed, the pin 32 is adapted to enter the hole 16. The pin 34 functions as a pressing-out pin when the mold is opened. The pins 32 and 34 form ~~a through hole 32~~ a through hole 44 in the molding material 40 in which the optical fiber 30 is inserted. Therefore, the pins 32 and 34 are of a shape corresponding to that of the optical fiber 30.

Changes to Claims:

Claims 27 and 34 are canceled.

Claims 35 and 36 are added.